

T-5500

**NEW**

For over 40 years now, Tresky has been synonymous for perfect micro-assembly equipment in the world of R&D and small-scale production. Customers know and love Tresky because the equipment is so easy to learn and use: you can be productive from day one. Manufactured with Swiss precision and dedication to engineering, the machines can remain in use for many years, and they can be adapted and expanded for a large variety of new and evolving applications, keeping the investment always at the cutting edge of technology.

Tresky's **T-5500** adds a **High Force Machine** to the line of the **T-5100** and **T-5300**. The sophisticated design of the integrated HF-module, **up to 100Kg**, in combination with the **Tresky True Vertical Technology** ensures an absolute coplanarity between chip and substrate at any height and force during the bonding process.

The **T-5500** is equipped with a motorized, programable Z-axis and new with a motorized Theta-axis (spindle rotation). The **T-5500**, with its Bonding Force up to 100Kg, really shines in applications with highest precision requirements in Thermocompression Bonding, such as **Sinter-Bonding** and Flip-Chip.

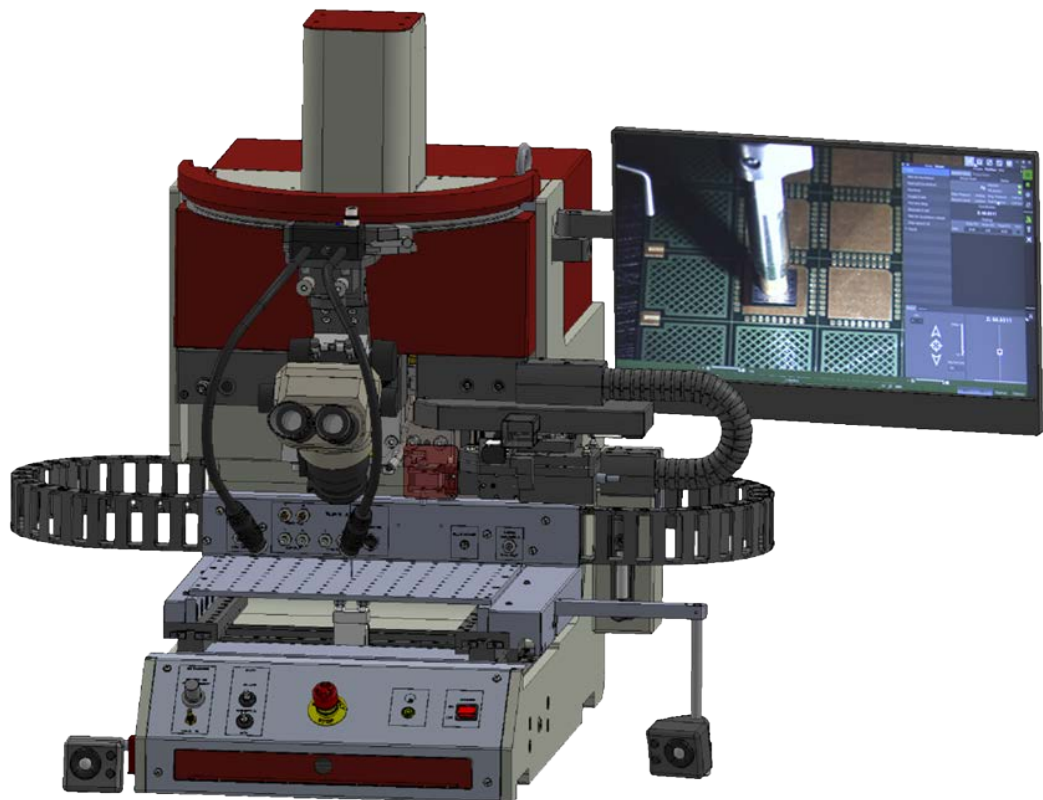
(Pre-) Sinter Bonding **Thermocompression Bonding** **Eutectic Die Bonding**

Flip-Chip **Sub-Micron Alignment Accuracy** **Epoxy Dispensing/Stamping**

Pick from Waffle/Gel Pack **Ultrasonic** **UV Curing**

MICRO ASSEMBLY

T-5000 SERIES



TRESKY

Advanced multi functional Die Bonder with superior ergonomic design and programmable, high accuracy Z-Drive and active bonding force control.

APPLICATIONS

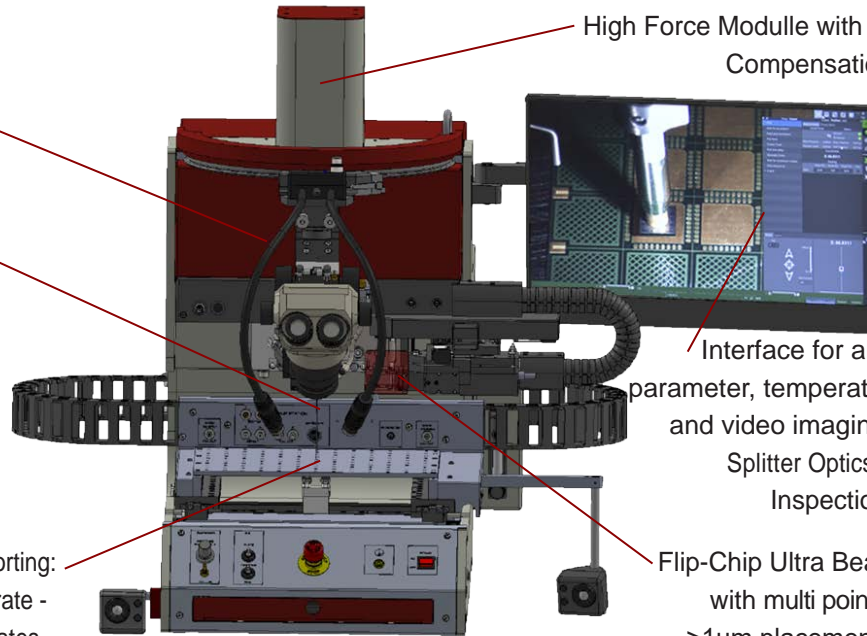
Pre-Sintering, Thermocompression, Die Attach, Flip-Chip, 3D Packaging, MEMS, MOEMS, VCSEL, Photonics, Ultrasonic, Thermosonic, RFID, Sensor Assembly, UV Curing, Eutectic Bonding (AuAu, AuSn,),

FEATURES AND OPTIONS

- Z-Drive with Active Bonding Force Control

- TRUE VERTICAL TECHNOLOGY™
Z-movement 125mm with 360° Tool rotation; Dispenser, Stamping, Ultrasonic, Scrub, Tool Heating, Pre Form, ...

- XY placement stage supporting: Waffle/Gel - Pack -, Substrate - Holder, various Heating Plates



- High Force Module with integrated Compensations Frame

- Interface for all bonding parameter, temperature profile and video imaging of Beam Splitter Optics, Process Inspection Camera

- Flip-Chip Ultra Beam Splitter with multi point alignment >1µm placement accuracy

TECHNICAL DATA

XY- Movement (placement stage):	220mm x 220mm	(manual)
Z- Movement:	120mm	(automatic)
Spindle Rotation (T):	360°	(motorized)
Bond Force (standard range):	20g - 100Kg	(other force ranges on request)
Z-Measurement resolution:	±0.001mm	
Max. PC Board-/ Substrate Size:	400mm x 280mm	
Placement accuracy:	±10µm; >±1µm optional	(process depending)
Optical Resolution (Flip-Chip Optic 1x option):	1.25µm	
Optical Resolution (Flip-Chip Optic 2x option):	0.625µm	
Connections:	Compressed air 5 - 6 bar / Vacuum 0.6 bar (abs)	
Dimensions:	900mm x 800mm x 750mm	
Weight:	95kg	
Voltage:	110V / 220V	

Note: All specifications are subject to change without notice

Represented by



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